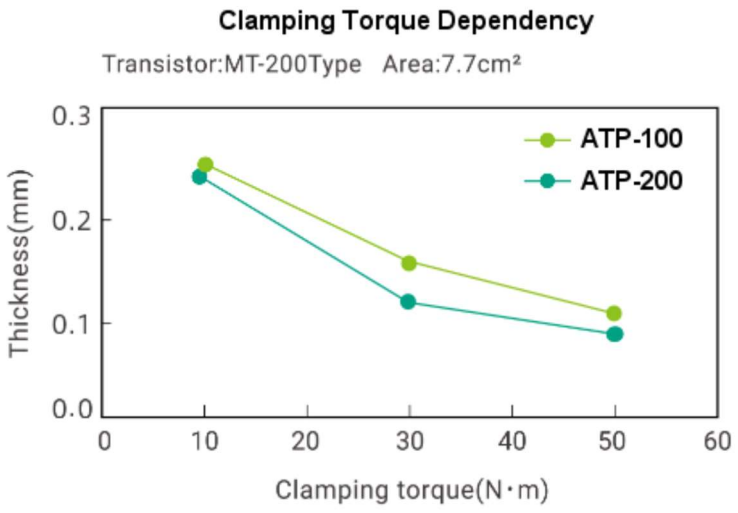
THERMAL PASTE

series: ATP

- **Eliminates air gaps between heat source and heat sink.**
- **High thermal conductivity of up to 6.5w/mk.**
- **Molecular structure prevents leakage and vaporization.**
- **Long term reliability.**
- **Good electrical insulation.**
- **Low rebound reduces load on electronic components.**
- **Compresses easily, absorbing dimensional tolerances.**
- **Typical applications include PCBs in automotive navigation systems, CIDs and ECUs, tablet devices, digital cameras, digital signage and manufacturing equipment.**

Properties		ATP-100	ATP-200
Thermal Conductivity (W/m-k) – Our tests Hot wire method		6.5 2.0	4.8 1.6
Hardness (Cone Penetration (1/10mm), not mixed		51	55
Appearance		Gray	Gray
Specific Gravity		2.8	2.6
Volume Resistivity (Ω.cm)		5.9x10	7.2x10
Dielectric Breakdown Strength (kV/mm)		5.0	5.6
Dielectric Constant <50Hz> <1KHz> <1MHz>		8.9 7.8 7.0	7.6 6.7 6.6
Dielectric Dissipation Factor <50Hz> <1KHz> <1MHz>		0.234 0.061 0.015	0.017 0.007 0.005
Thermal Resistance (°C/W) Transistor: MT-200 Heat Input: 20V	Thickness (mm) 0.10	-	0.13
	0.15	0.13	-
	0.20	0.15	0.17
	0.30	0.18	0.22
Low Molecular Weight Siloxane Level D4-10 (ppm)	Solvent Extraction Method	Less than 700	Less than 900
	Head Space Method	Less than 1	Less than 3
Temperature Range (°C)		-40 ~ 200	-40 ~ 200



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Heat input: 20V
(°C)